



GlobalFoundries™

**Delivering essential
semiconductors for
humankind**

Disclaimer

This presentation and the accompanying oral presentation include “forward-looking statements,” that reflect our current expectations and views of future events. These forward-looking statements are made under the “safe harbor” provisions of the U.S. Private Securities Litigation Reform Act of 1995 and include but are not limited to, statements regarding our financial outlook, future guidance, product development, business strategy and plans, and market trends, opportunities and positioning. These statements are based on current expectations, assumptions, estimates, forecasts, projections and limited information available at the time they are made. Words such as “expect,” “anticipate,” “should,” “believe,” “hope,” “target,” “project,” “goals,” “estimate,” “potential,” “predict,” “may,” “will,” “might,” “could,” “intend,” “shall,” “outlook,” “on track,” and variations of these terms or the negative of these terms and similar expressions are intended to identify these forward-looking statements, although not all forward-looking statements contain these identifying words. Forward-looking statements are subject to a broad variety of risks and uncertainties both known and unknown. Any inaccuracy in our assumptions and estimates could affect the realization of the expectations or forecasts in these forward-looking statements. For example, our business could be impacted by the COVID-19 pandemic and supply chain disruptions due to the Russia/Ukraine conflict and actions taken in response to such events; the market for our products may develop more slowly than expected or than it has in the past; our operating results may fluctuate more than expected; there may be significant fluctuations in our results of operations and cash flows related to our revenue recognition or otherwise; a network or data security incident that allows unauthorized access to our network or data or our customers’ data could damage our reputation; we could experience interruptions or performance problems associated with our technology, including a service outage; and global economic conditions could deteriorate. It is not possible for us to predict all risks, nor can we assess the impact of all factors on our business or the extent to which any factor, or combination of factors, may cause actual results or outcomes to differ materially from those contained in any forward-looking statements we may make. Moreover, we operate in a competitive and rapidly changing market, and new risks may emerge from time to time. You should not rely upon forward-looking statements as predictions of future events. These statements are based on our historical performance and on our current plans, estimates and projections in light of information currently available to us, and therefore you should not place undue reliance on them.

Although we believe that the expectations reflected in our statements are reasonable, we cannot guarantee that the future results, levels of activity, performance or events and circumstances described in the forward-looking statements will be achieved or occur. Moreover, neither we, nor any other person, assumes responsibility for the accuracy and completeness of these statements. Recipients are cautioned not to place undue reliance on these forward-looking statements, which speak only as of the date such statements are made and should not be construed as statements of fact. Except to the extent required by federal securities laws, we undertake no obligation to update any information or any forward-looking statements as a result of new information, subsequent events, or any other circumstances after the date hereof, or to reflect the occurrence of unanticipated events.

This presentation and the accompanying oral presentation also contain estimates and other statistical data made by independent parties and by us relating to market size and growth and other data about our industry and business. This data involves a number of assumptions and limitations, and you are cautioned not to give undue weight to such estimates. We have not independently verified the industry data generated by independent parties and contained in this presentation and, accordingly, we cannot guarantee their accuracy or completeness. In addition, projections, assumptions, and estimates of our future performance and the future performance of the markets in which we compete are necessarily subject to a high degree of uncertainty and risk.

In addition to the financial information presented in accordance with International Financial Reporting Standards (“IFRS”), this presentation includes the following adjusted non-IFRS metrics: adjusted gross profit (loss), adjusted gross margin, adjusted net income (loss), adjusted diluted earnings (loss) per share and adjusted EBITDA. We define adjusted gross profit (loss) as gross profit (loss) adjusted for share-based compensation expense. We define adjusted gross margin as adjusted gross profit (loss), which is gross profit (loss) before share-based compensation, divided by net revenues. We define adjusted operating profit (loss) as profit (loss) from operations adjusted for share-based compensation expense. We define adjusted operating margin as adjusted operating profit (loss) divided by net revenues. We define adjusted net income (loss) as net income (loss) adjusted for share-based compensation expense. We define adjusted diluted earnings (loss) per share as adjusted net income (loss) divided by the dilutive shares. We define adjusted EBITDA as net income (loss), excluding the impact of finance expense, income tax expense, depreciation, amortization, share-based compensation expense, transaction gains and associated expenses, restructuring charges and litigation settlements. We define adjusted EBITDA margin as adjusted EBITDA divided by net revenues.

We believe that in addition to our results determined in accordance with IFRS, these adjusted non-IFRS measures provide useful information to both management and investors in measuring our financial performance and highlight trends in our business that may not otherwise be apparent when relying solely on IFRS measures. These adjusted non-IFRS financial measures provide supplemental information regarding our operating performance that excludes certain gains, losses and non-cash charges that occur relatively infrequently and/or that we consider to be unrelated to our core operations. For further information regarding these non-IFRS measures, please refer to “Appendix” in this presentation.

Adjusted non-IFRS financial information is presented for supplemental informational purposes only and should not be considered in isolation or as a substitute for financial information presented in accordance with IFRS. Our presentation of adjusted non-IFRS measures should not be construed as an inference that our future results will be unaffected by unusual or nonrecurring items. Other companies in our industry may calculate these measures differently, which may limit their usefulness as a comparative measure.



**Delivering a
new era of more**



**more
innovation**



**more
impact**

GF at a glance

\$8.1B

2022 revenue

2.5M

2022 wafer shipments
(300mm eq.)

200+

customers in 2022

4

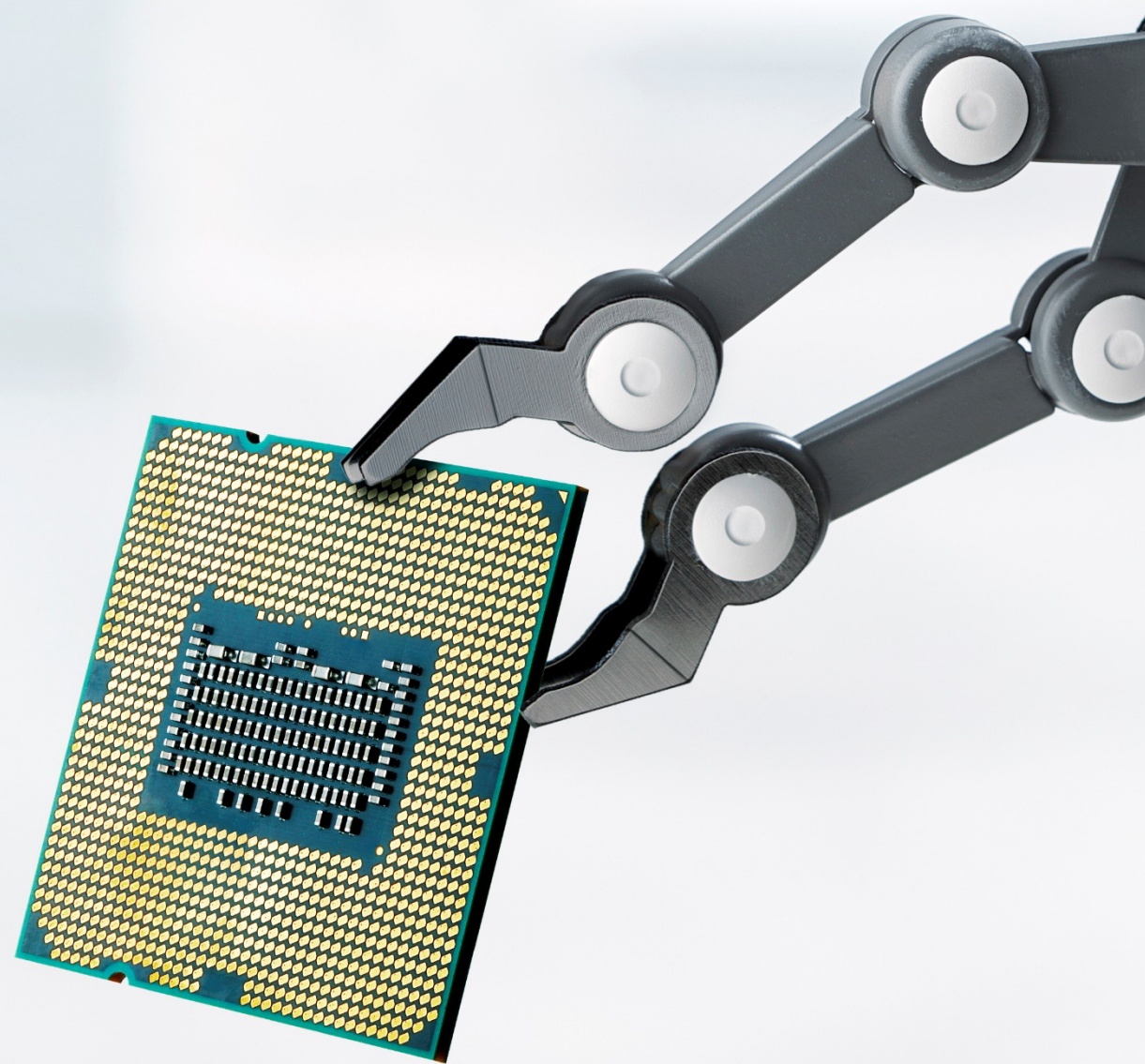
manufacturing sites
across three continents

~13,000

employees

~9,000

patents



GF journey

Creation

GlobalFoundries was created based on the thesis that the world needed a geographically diverse alternative to Taiwan



2009

2017

2018

Transformation

Strategically re-positioned to serve pervasive semiconductor end markets

- Strengthened management team aligned to mission
- Refocused investments & accelerated differentiated solutions focused on pervasive markets
- Increased single-sourced products
- Driving margin expansion and earnings growth



2021

2022

Realization

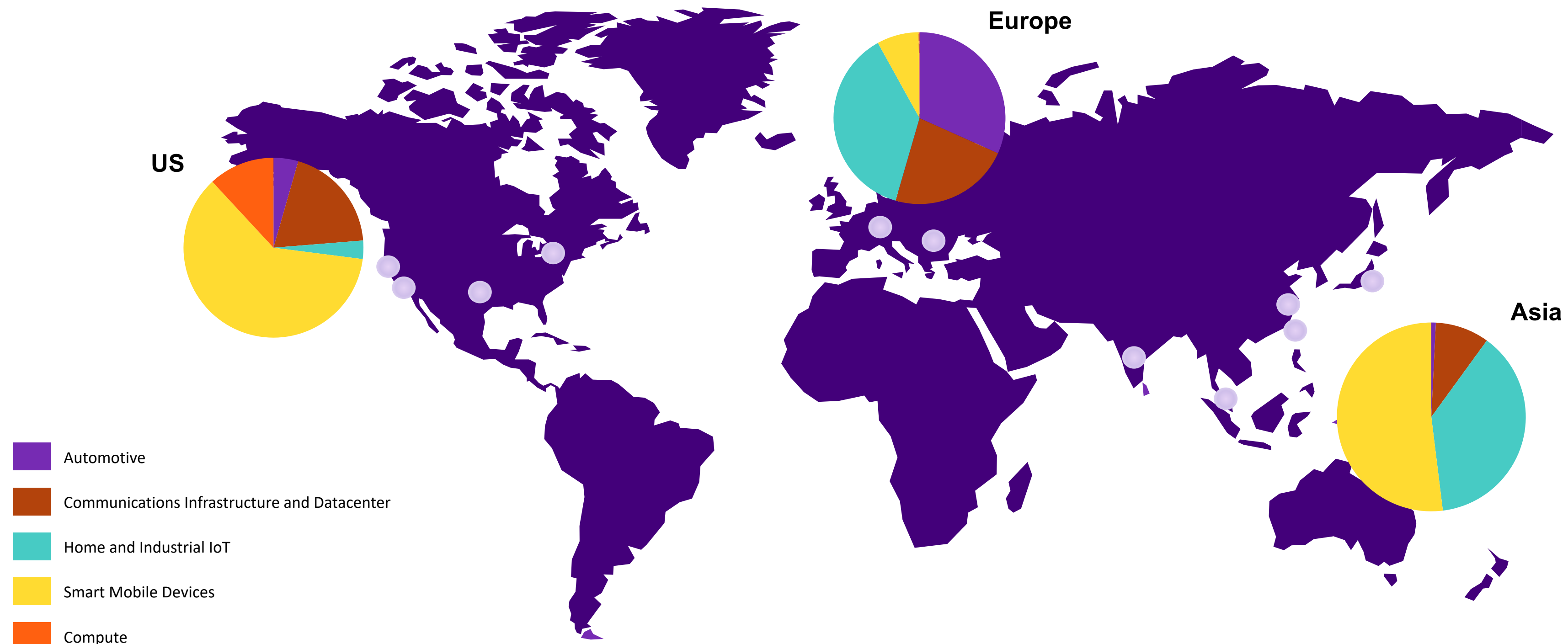
The world's leading manufacturer of feature-rich semiconductor solutions

- Gain share in secular end-markets
- Innovate in purpose-built platforms and solutions
- Capital efficient expansion through partnerships
- Deliver best-in-class financials



2030

Delivering solutions to customers around the globe



- Automotive
- Communications Infrastructure and Datacenter
- Home and Industrial IoT
- Smart Mobile Devices
- Compute
- GF Field Site



10
Countries
and time zones

11
Service
languages

<10 km
Median proximity
to top customers

Purpose-built customer engagements

Certainty

~80%
2022-2025 capacity covered by LTAs

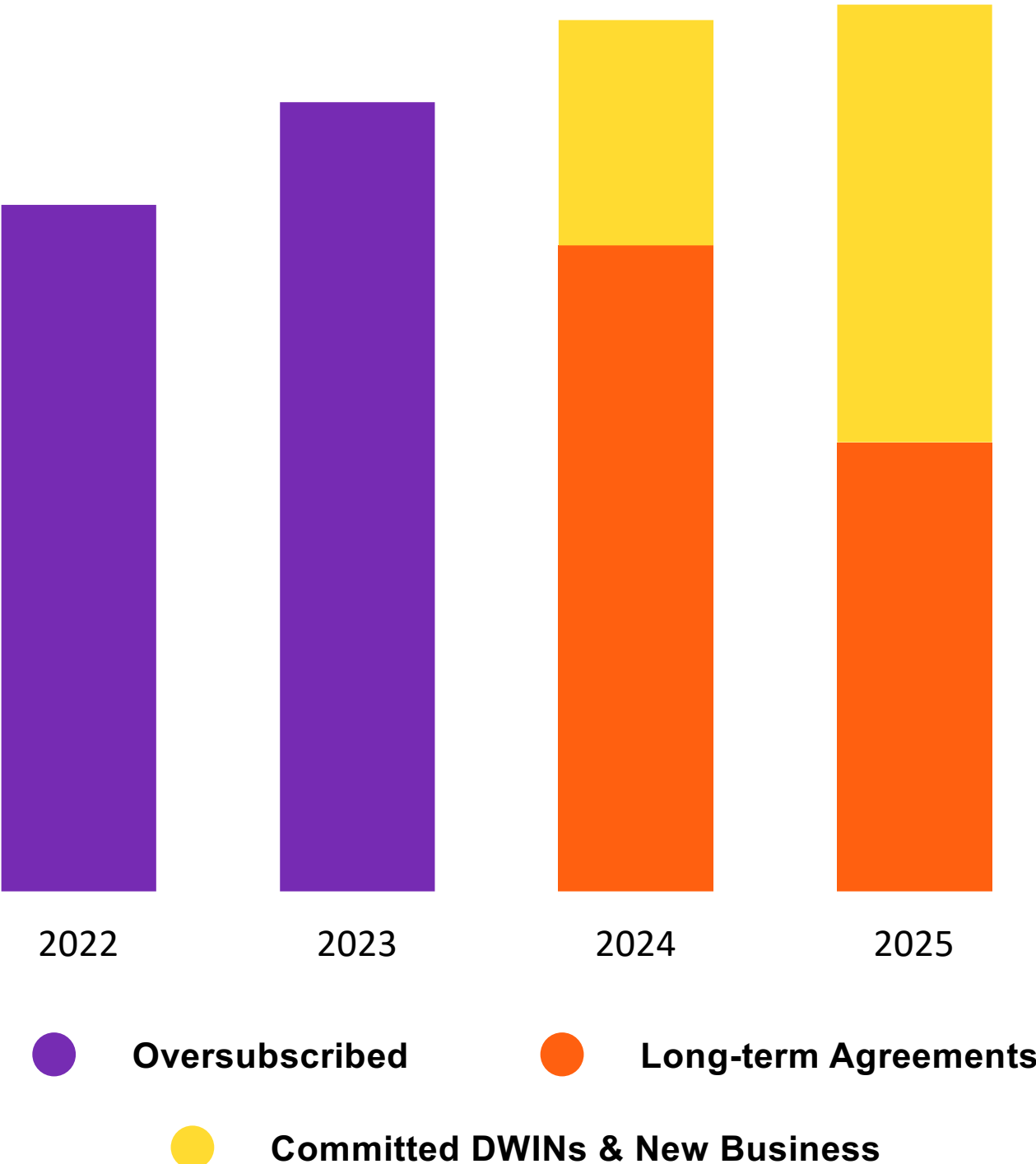
Durability

90%
single-sourced DWINs⁽¹⁾ in 1H'22

Profitability

↑19%
YoY mix and pricing increase 1H'21 - 1H'22⁽²⁾

Multi-year Capacity Coverage



Note:
 1. A DWIN, or design win, is defined as the successful completion of the evaluation stage, where a customer has assessed our technology solution, verified that it meets its requirements, qualified it for their products and confirmed to us their selection.
 2. Wafer hardware only

GF's ecosystem: more than a decade in the making

Design enablement network

IP	FDX™	RF	EDA	Design services	OSAT

Our partner community

- 100+**
Ecosystem partners spanning IP, EDA, OSAT and design services
- 4500+**
Total IP titles across all nodes from >50 IP partners
- 950+**
IP titles currently in active development across 26 process nodes and 34 IP partners
- 300+**
Clients enabled by ecosystem partner IPs in the last 5 years
- 1700+**
Client designs enabled by ecosystem partners in the last 5 years



- **End-markets**
- **and Solutions**

Technology megatrends shaping the global economy

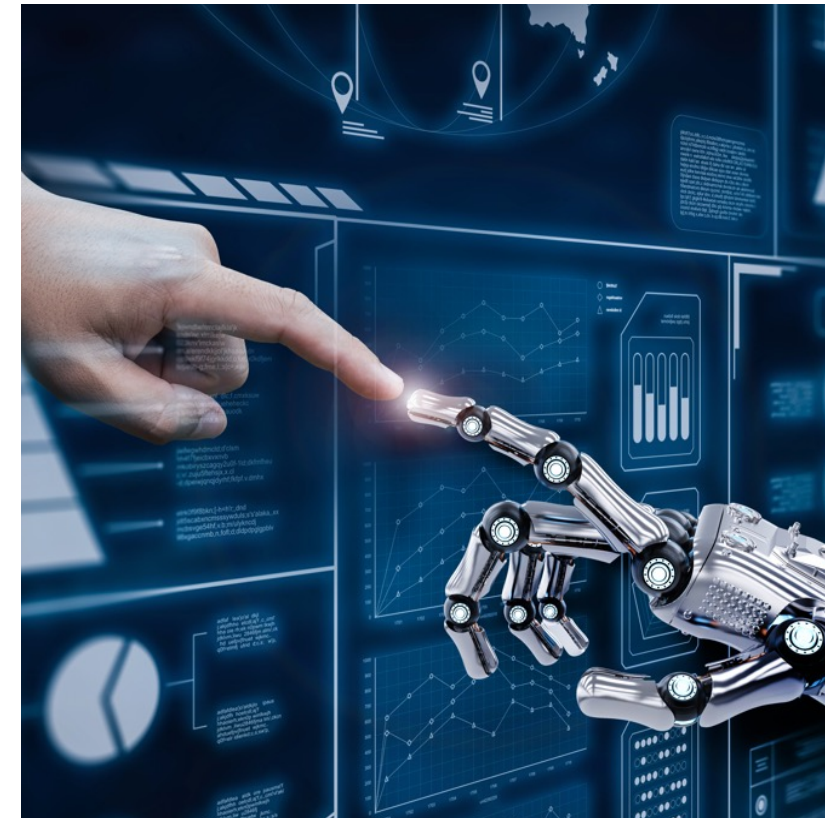
Smart, connected devices



Adoption of AR & VR



Explosion of AI & ML



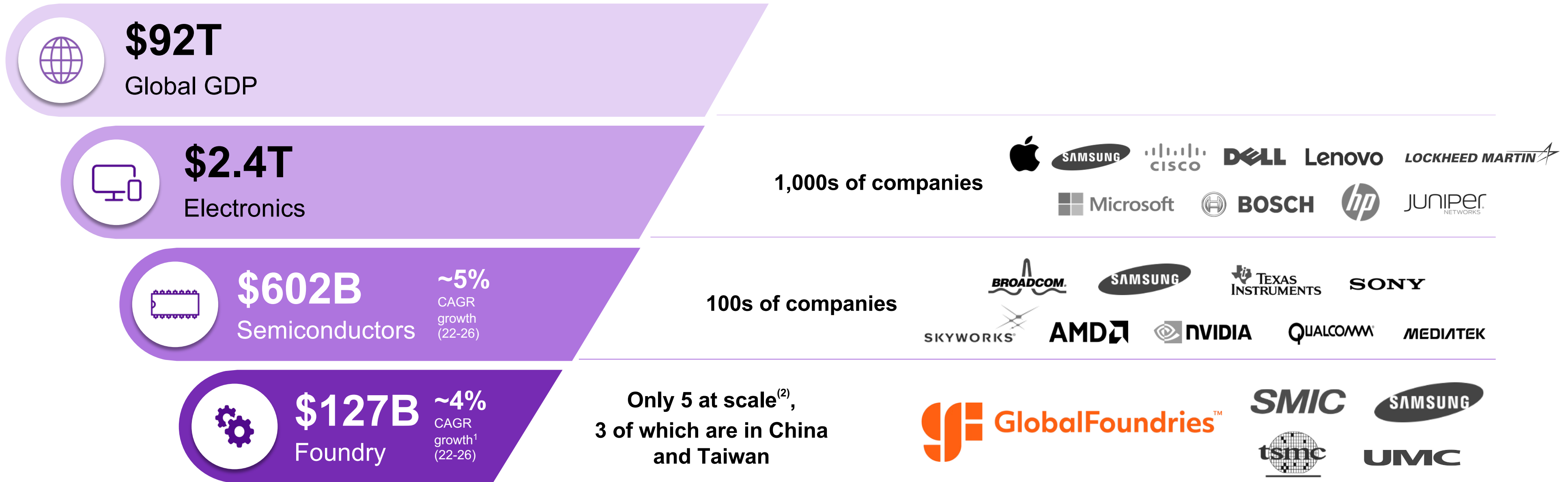
Data everywhere



Megatrends accelerated or limited by semiconductors

Foundries are essential to global GDP

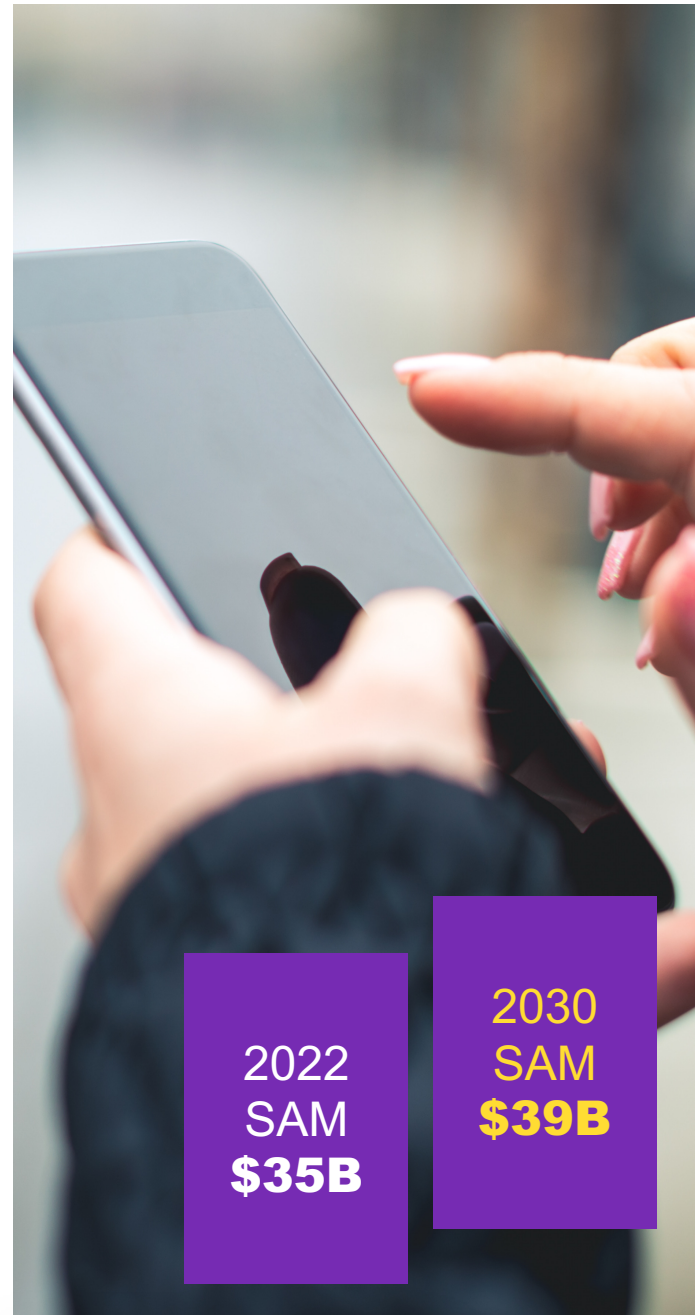
Market Size (2022)



Source: Global GDP: World Bank, IMF. Electronics; Semiconductors and Foundry: Gartner "Forecast, Semiconductor Foundry Revenue, Supply and Demand, Worldwide, 4Q22 Update (December 2022)

Note:
 1. Excluding memory
 2. Excludes smaller foundry players, defined as those with less than \$2Bn of foundry revenue

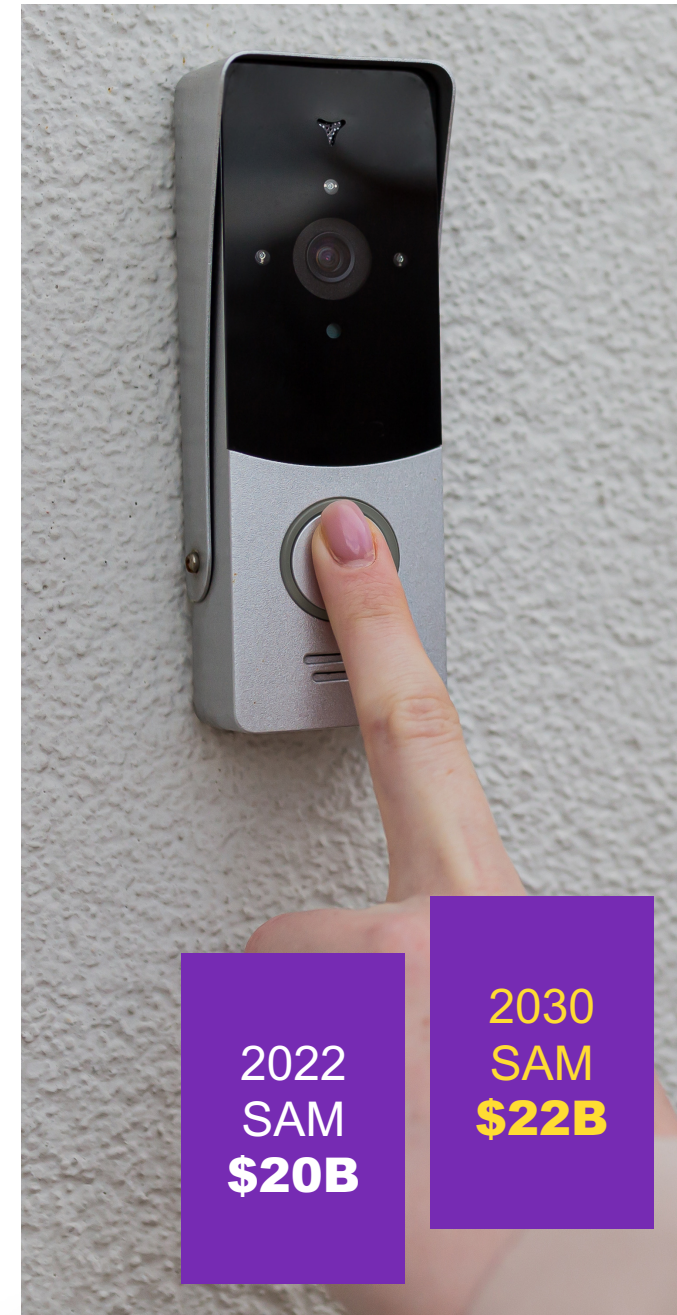
Uniquely positioned in markets that matter



Smart Mobile Devices



Automotive



Home and Industrial IoT



Communications Infrastructure & Datacenter



Aerospace, Defense & Critical Infrastructure

Smart Mobile Devices

4G LTE/5G: RF FE Sub-6GHz

RF SOI
Higher Data Rate
Power Efficiency

5G: RF FE mmWave

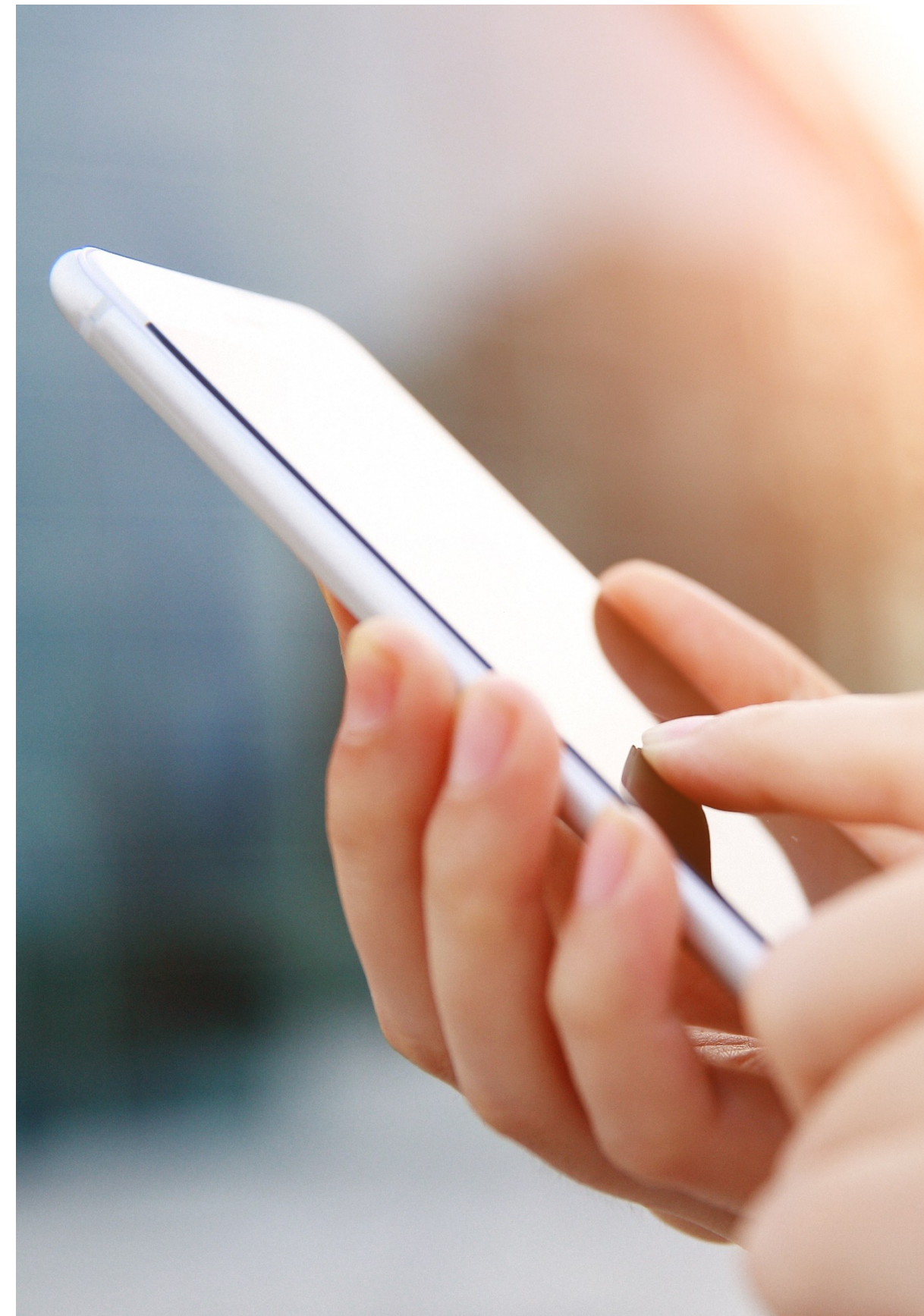
FDX™
Expanded Range
Power Efficiency

4G LTE/5G: Transceiver

FinFET
Higher Data Rate
Power Efficiency

Wi-Fi: Wi-Fi 6/6E

FinFET
Higher Data Rate
Power Efficiency



Camera: Optical Imaging

Feature-Rich CMOS
Sensor Fusion
Power Efficiency

Smart Audio

Feature-Rich CMOS (BCD, eNVM)
Audio Quality
Haptic Response

Secure Payment: NFC

Feature-Rich CMOS (eNVM)
Integration of NFC+ Secure Element
Secure Manufacturing

Touch Screen: Display

Feature-Rich CMOS
Functional Integration
Power Efficiency

Power Management: RF, Audio

Feature-Rich CMOS (BCDLite®), FDX™
Increased Efficiency
Smaller Form Factor

Home and Industrial IoT

Smart Camera: Image Sensing

FDX™

Edge Intelligence
Low Power Connectivity

Smart Features: SoC

Feature-Rich CMOS

High Transfer Rate
Power Efficiency
Edge Intelligence

Smart Control: WL MCU

FDX™

Power
Wireless (BLE, Wi-Fi, 15.4)

Smart Features: MCU

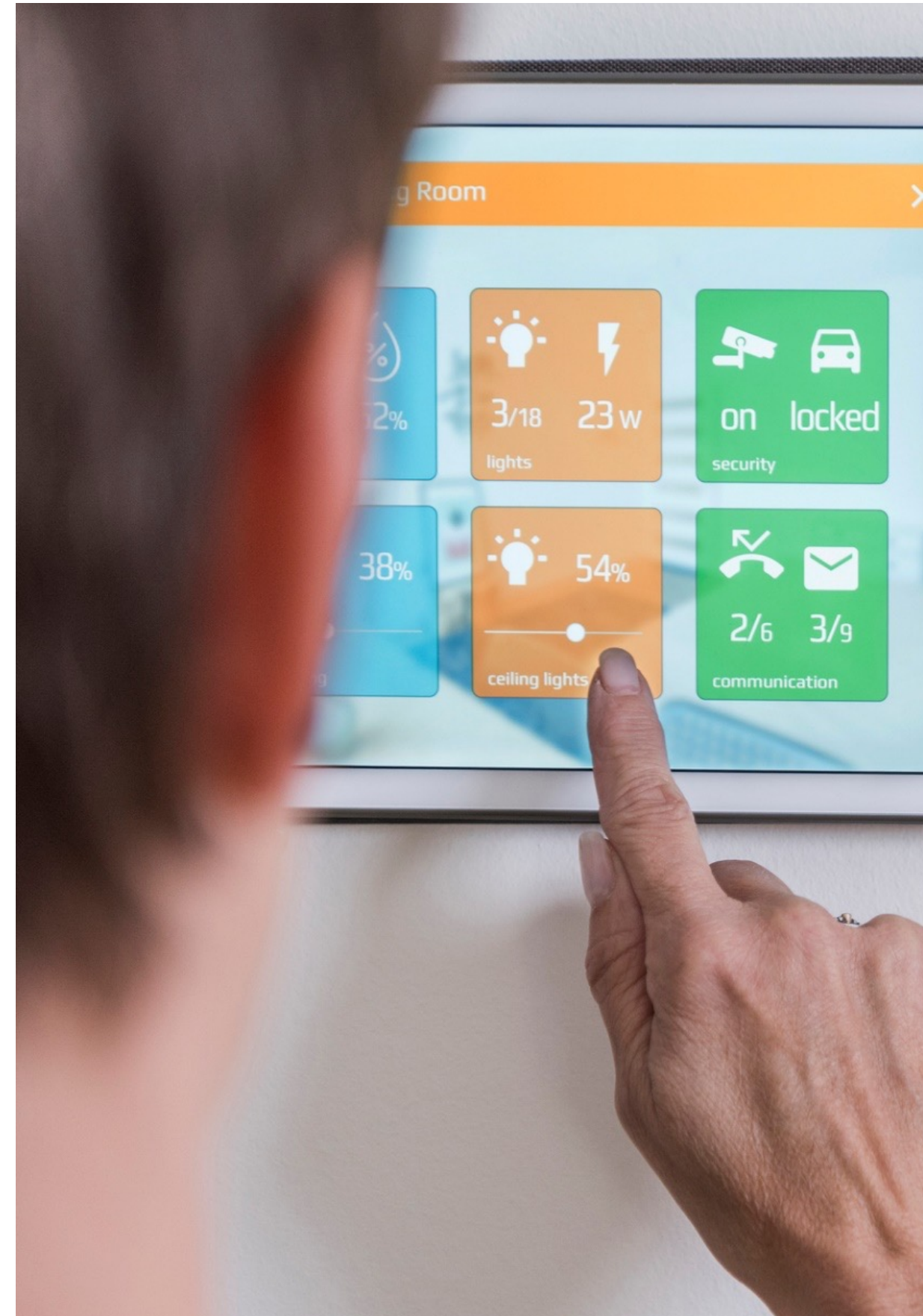
Feature-Rich CMOS (BCD)

Power Management

Secure Transactions/ Interactions: NFC

Feature-Rich CMOS (eNVM)

Power Efficiency



Smart Speaker: Audio

Feature-Rich CMOS (BCD, eNVM)

Power Efficiency
Power Management

Wi-Fi Connection: Wi-Fi

FDX™

Edge Intelligence
Low Power Connectivity

Touch Screen: Display

Feature-Rich CMOS

Sensor Fusion
Power Efficiency

Medical IoT: Medical Sensing

FDX™

Edge Intelligence
Low Power Connectivity

Automotive

5G Connection: RF FEM mmWave

FDX™
RF mmWave
Low Power Connectivity

Vehicle Power: DC-DC, BMS, Charger

Feature-Rich CMOS (BCD, eNVM)
High Voltage
Precision
Power Efficiency
Power Management

Vehicle Network: Zone/Domain/Fusion

Controllers

FDX™, FinFET
Power Efficiency
High Performance
High Temperature

Comfort/Customization/ Keyless Entry: MCU,

NFC, BLE, UWB

Feature-Rich CMOS (eNVM)
Power Efficiency
Edge Intelligence



ADAS: Radar

FDX™
RF mmWave
Power Efficiency
Edge Intelligence

Touch Screen: Display

Feature-Rich CMOS
Sensor Fusion
Power Efficiency

ADAS: LiDAR

Silicon Photonics
High Transfer Rate
Power Efficiency
Edge Intelligence

User Experience: IVI, Cluster

Feature-Rich CMOS (BCD)
Power Efficiency
Power Management

Communications Infrastructure & Datacenter

5G Infrastructure:

RF FEM mmWave

RF SOI, SiGe, 22FDX®

RF mmWave

Power efficiency

5G Infrastructure:

Network processor /

Switch

FinFET, Feature-Rich CMOS

Performance analog/mixed signal

Data

communications:

Redriver

SiGe

Signal loss compensation

Data reliability & integrity

4G LTE/5G

Infrastructure: RF

FEM Sub-6GHz

RF SOI, SiGe

RF features

Power efficiency



Connectivity:

Optical networking

Silicon Photonics

Data throughput >4x Cu

Cu replacement for inter and intra DC connectivity

Chiplets/2.5D/3D: IOD

FinFET

Performance analog/mixed signal

Novel compute:

AI/Photonics/Quantum

FinFET, Silicon Photonics

System integration: electronics & photonics

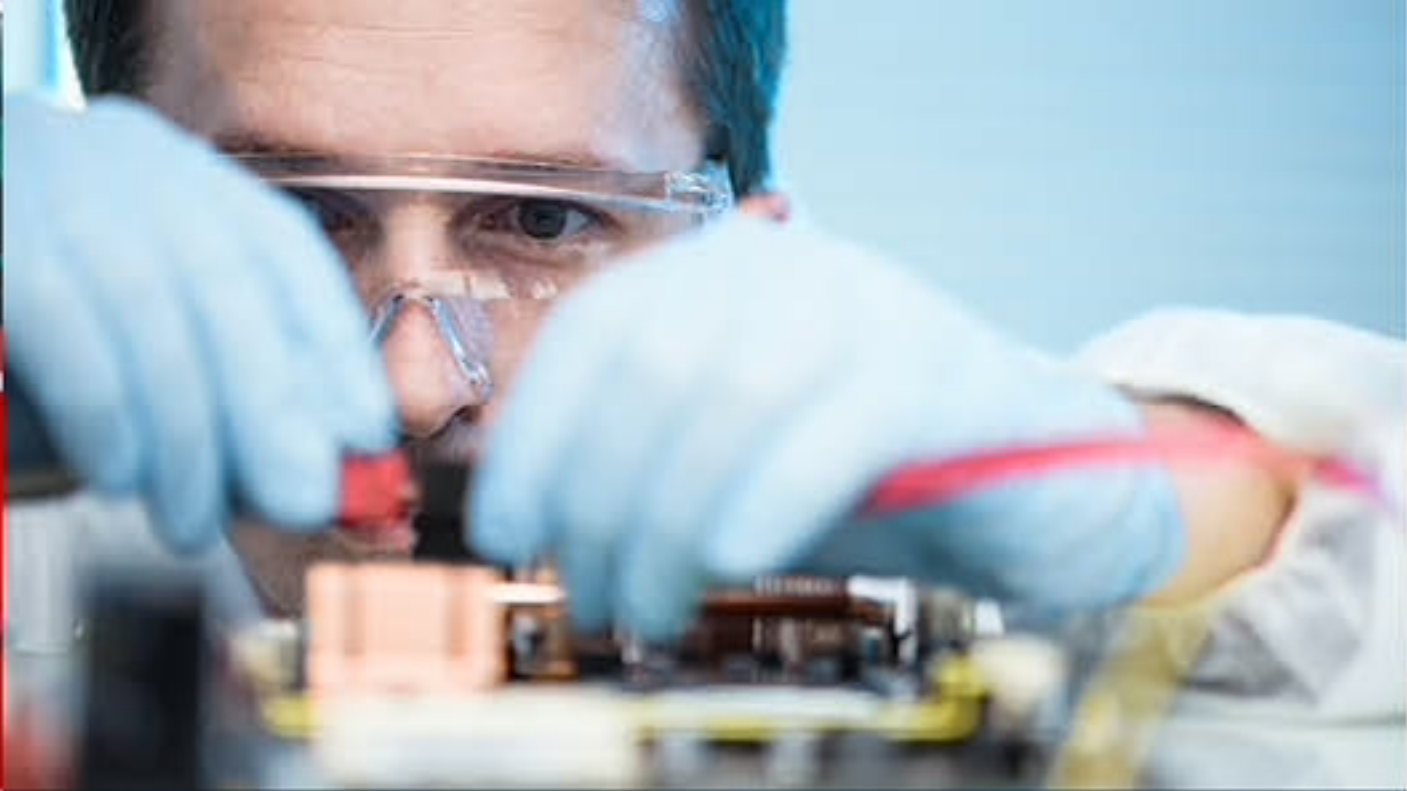
Highest performance/power efficiency

Power delivery

Feature-rich CMOS (BCDLite®)

High Voltage

High efficiency



GF is everywhere





Global



Footprint

Manufacturing at a glance



99%

line yield up
to 15 years reliability

>31M

hours worked in 2020 at better
than safety benchmarks

4

manufacturing sites
across three continents

800 NPIS

per year, ramped in 6-
9 months to HVM

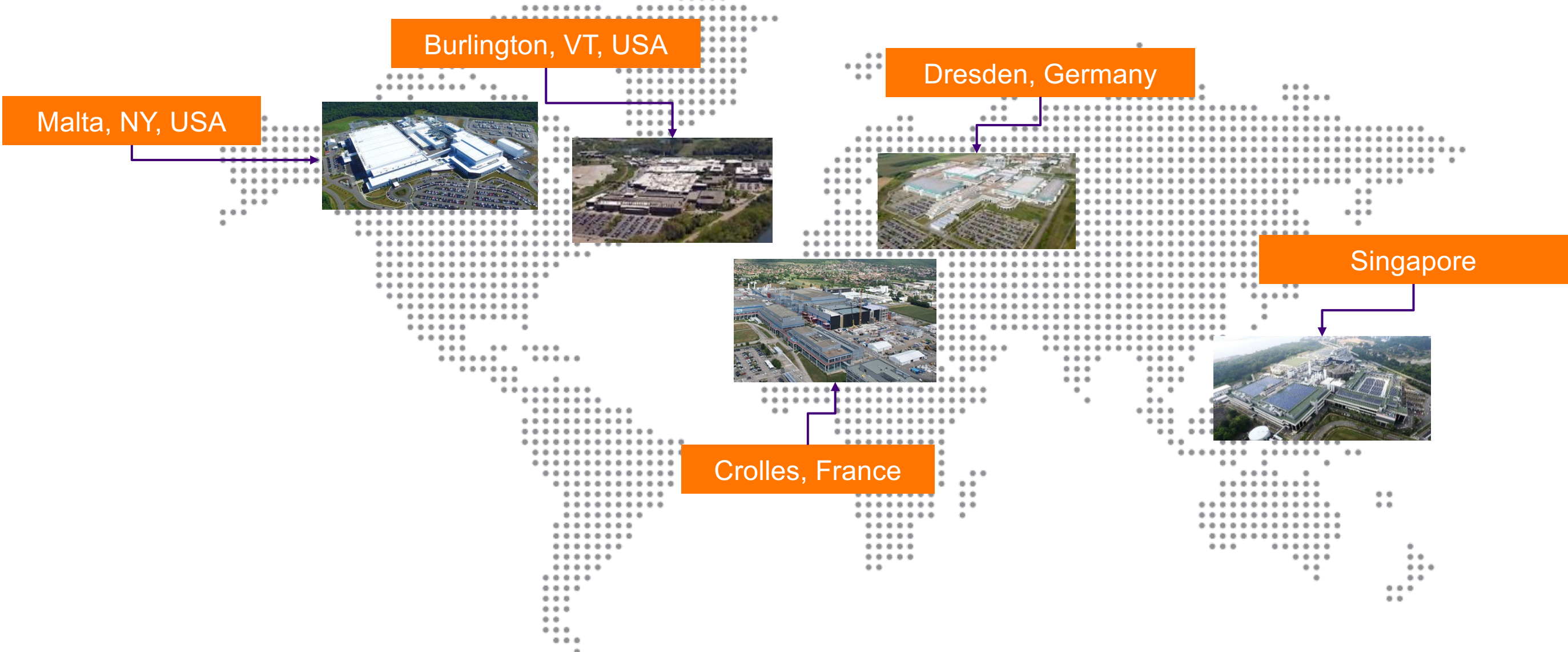
99%

on time delivery

Zero

stock outs impacting customer
commitments

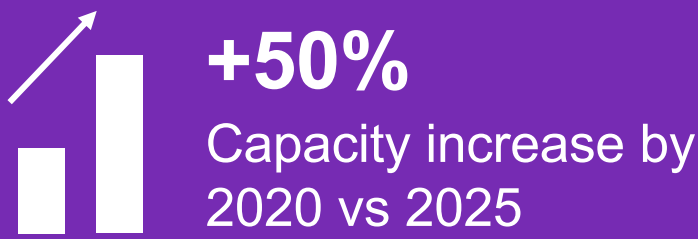
Global manufacturing footprint & strategy



Supply chain security through dual-technology qualification



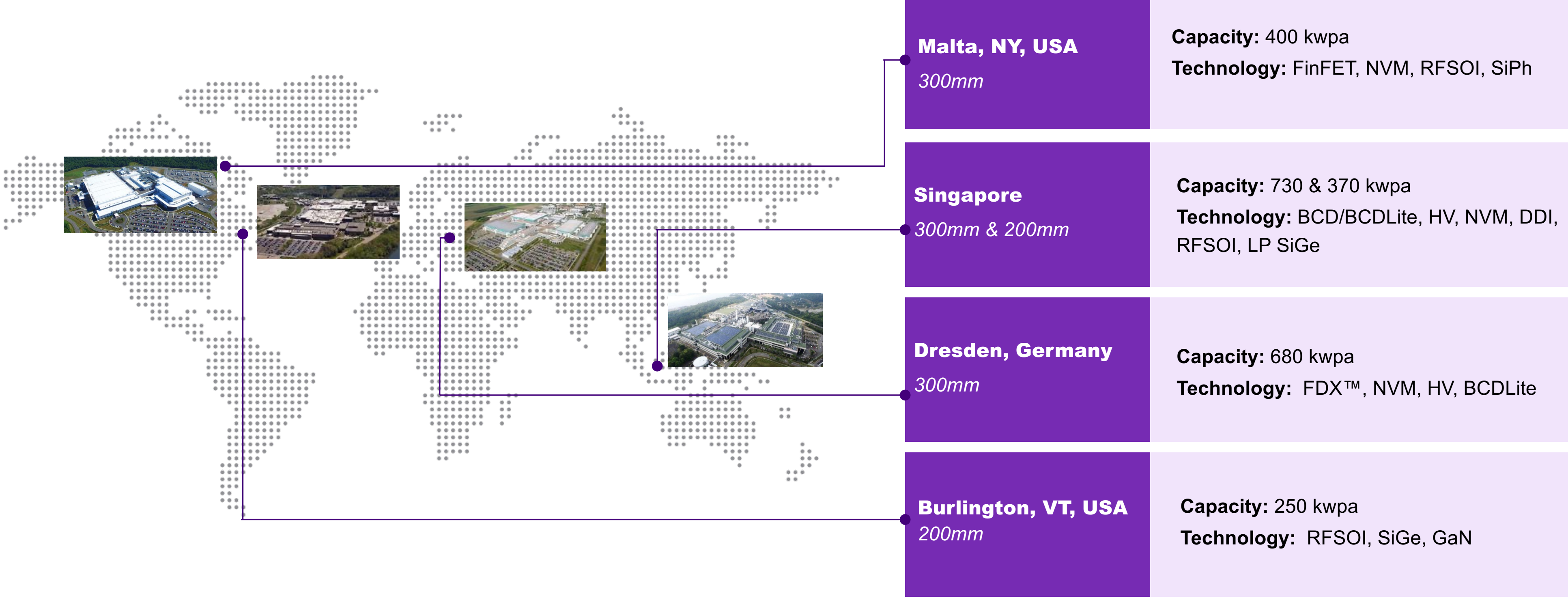
Economies of scale through modular expansion at existing sites



Capital efficiency through partnership model

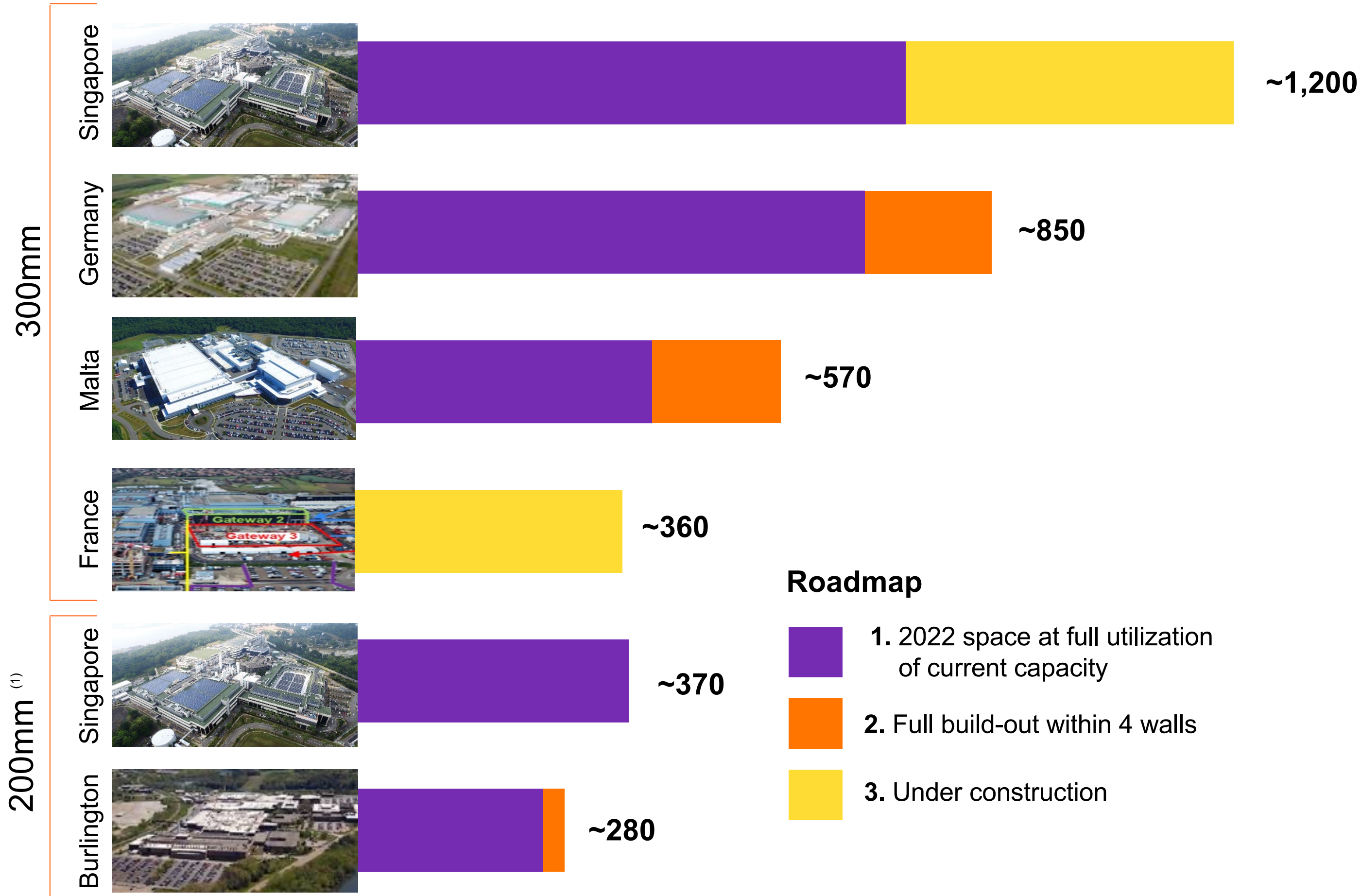


Global manufacturing footprint - current



Note:
 1. Kwpa is defined as 2022 capacity in thousand wafers per annum
 2. 200mm capacity translated to 300mm equivalent

Capacity expansion roadmap



Global manufacturing FOOTPRINT focused on supply security, diversity & sustainability

>50% capacity expansion from 2020 levels

Economy of scale through modular expansion at existing sites in global footprint

Dual site sourcing provides flexibility & security

25% GHG reduction in emissions by 2030

Roadmap

- 1. 2022 space at full utilization of current capacity
- 2. Full build-out within 4 walls
- 3. Under construction

Notes:

1. 200mm capacity translated to 300mm equivalent, in kwa.
2. Full build up Plan through 2028.
3. Does not include future capacity plans under development

Global manufacturing footprint – beyond '23



Malta, NY, USA 300mm	Capacity: 570 kwp Technology: FinFET, NVM, RFSOI, SiPh
Singapore 300mm & 200mm	Capacity: 1,200 kwp & 370 kwp Technology: BCD/BCDLite, HV, NVM, DDI, RFSOI, LP SiGe
Dresden, Germany 300mm	Capacity: 850 kwp Technology: FDX™, NVM, HV, BCDLite
Burlington, VT, USA 200mm	Capacity: 280 kwp Technology: RFSOI, SiGe, GaN
Crolles, France 300mm	Capacity: 360 kwp Technology: 22FDX®

Note:

1. Kwp is defined as 2022 capacity in thousand wafers per annum
2. 200mm capacity translated to 300mm equivalent



Crolles, France partnership with STMicroelectronics

GF & ST co-managed facility

- Production execution managed by ST supplemented by onsite GF technology expertise
- Joint oversight of all planning and operations
- Depreciation, fixed and variable cost sharing model based on actual utilization and consumption
- Stable and low-cost energy supply through French Nuclear energy network, and reduced environmental impact

Phase 0: Install 24 unique FDX™ tools to form pilot line for technology transfer in existing fab

Phase 1-3: Ramp volume production up to 360kwpa in extension buildings

Singapore modular expansion



Groundbreaking in June 2021

First tool into cleanroom in June 2022

Ramping production with market demand

>1.5M of 300mm equivalent wafers serving Auto, Mobile and IoT

Secured government grants and customer commitments



Malta, NY expansion

Expansion announced in July 2021

**Planning and preliminary
permitting underway**

**Strong government and
customer partnerships**

**CHIPS and Science Act signed into
law in August 2022**

Sustainable Operations

100%

of **3TG** minerals we use are conflict free

2015-2021

2022 and Beyond



38%

Reduction in electricity use intensity

33%

Reduction in electricity use intensity by 2025 ⁽¹⁾

Journey to

ZERO

Carbon



36%

Reduction in GHG emissions intensity

25%

Absolute reduction in GHG emissions by 2030 ^(1,2)

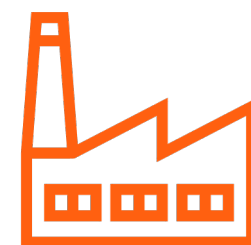


40%

Reduction in water use intensity

33%

Reduction in water use intensity by 2025 ⁽¹⁾



62,100

Tons annualized reduction of chemical use and waste

90%

Landfill avoidance in 2023

Note:

- 1. Improvement from 2020 Actuals
- 2. GHG emissions include scope 1 and 2



Technology



Development

Technology Development at a glance



~1400

technologists in dedicated research teams

30K+

wafers per year dedicated to development

50+

universities, government partners and other research institutes partnered in collaborative efforts

150+

differentiated programs built on 25+ world class platforms

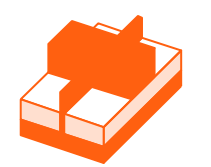
Innovation through market-driven purpose-built platforms

Optimizing digital processing & application specific features




Feature-Rich CMOS
Complementary Metal-Oxide Semiconductor

Mixed-technologies for power management, high-voltage, embedded memory




FinFET
Fin Field-Effect Transistor

High performance, power efficient "Systems-On-a-Chip"




FDX
Fully-Depleted SOI

Enabling new high-performance, low-power applications



RF SOI
RF Silicon-on-Insulator

Low power / low noise / low latency / high frequencies



SiPh
Silicon Photonics

Higher data rates with greater power efficiency



SiGe
Silicon Germanium

Power amplifier and very-high-frequency applications



WBG: GaN
Gallium Nitride

High efficiency power conversion

The ultimate in low power, performance with superior connectivity

Innovating beyond silicon

Innovation beyond transistor size

How we innovate: Smart Mobile Device

Ultra-fast, seamless, reliable connectivity

End user applications



Bridging the cellular and wireless experience effortlessly

Capabilities required



Rate



Range



Power

GF's differentiated performance

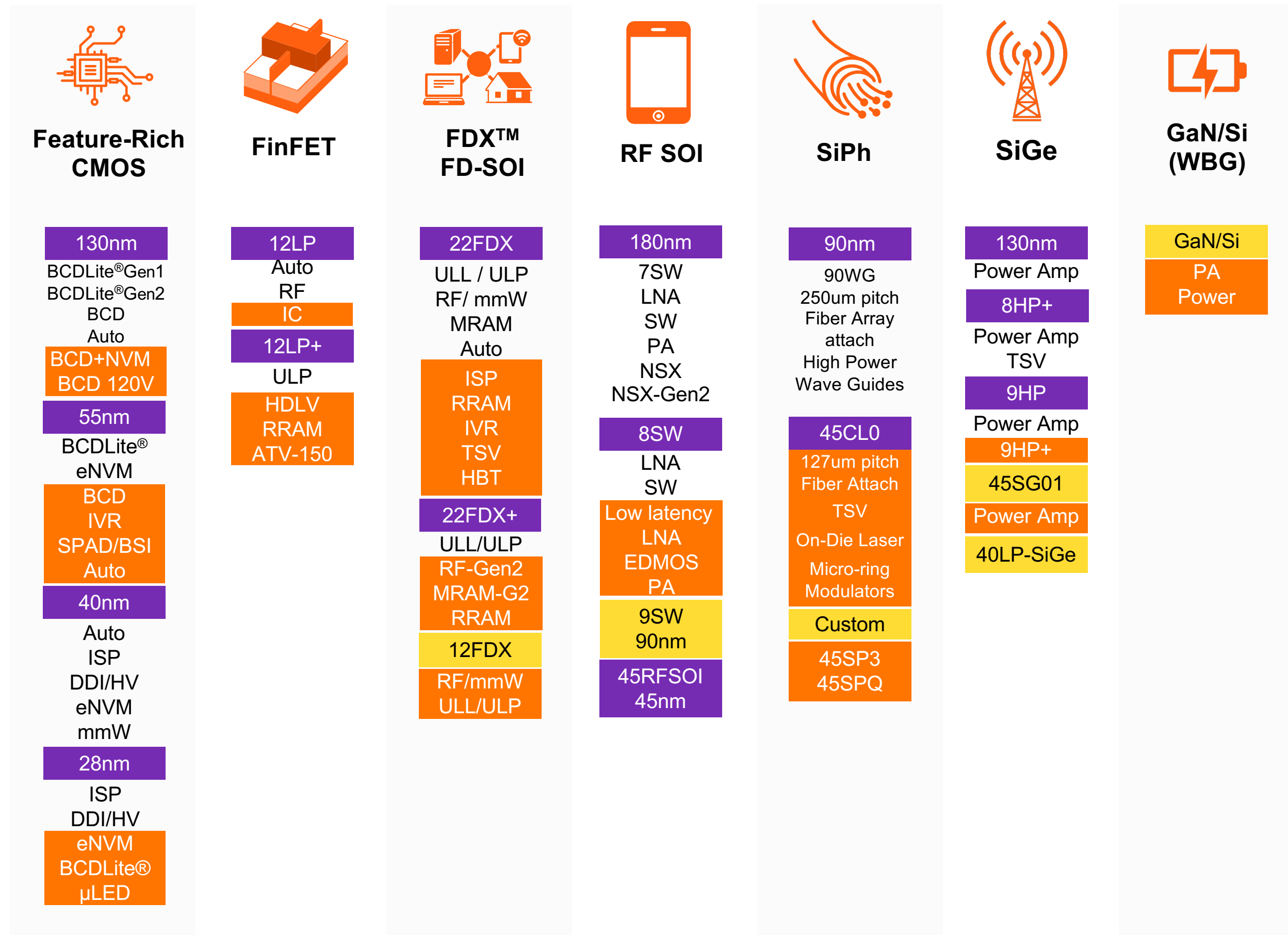
RF SOI

FDXTM

SiGe

GaN

Investing for a bold future



Huge features portfolio:
120 technology solutions enabling thousands of customer products

2022 expansion:
+16 technology solutions
+ 6 new platforms
+ dozens of new features in dev.

Beyond Si solutions:
Adding wide bandgap materials for power and RF – GaN/Si





Investing for 2030








Physical Sciences Innovation

-  Materials Enabling New Capabilities
-  New Devices to Extend and Expand Applications
-  Advanced Tooling and Processes






Design Innovation

-  System Level Architecture Explorations
-  Heterogeneous Integration
-  AI-enabled Design
-  Circuit Topologies

Partnership / Ecosystem

-  Expanded University Engagements
-  Customer Collaborative Projects
-  Government Supported and targeted R&D
-  Lab-to-Lab
-  Lab-to-Fab

Market Focus

-  6G and beyond
-  AR / VR
-  Datacenter
-  Quantum Computing
-  Automotive

Strategic University Partnerships



"We are excited to partner with GlobalFoundries to crystalize our offerings into programs relevant to the foundation of digital economy. We are intensifying our efforts not only to scale up the talent pipeline, but also to create the depth of innovation expertise needed to advance U.S. leadership in semiconductors."

Dr. Mung Chiang,
President-elect and Executive Vice President
of Purdue University

"Semiconductor research is a top priority for Georgia Tech and the nation, as we develop innovative solutions that improve manufacturing and support our national and state economies. Deepening our partnership with GlobalFoundries allows us to leverage our complementary technology and talent resources to benefit this vital industry, and to improve the human condition."

Chaouki Abdallah,
Executive Vice president for Research
at Georgia Tech

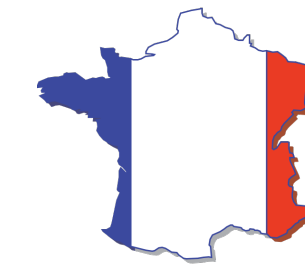
Joint partnerships to advance semiconductor innovation, while helping prepare and train a new generation of talented young people for careers in the semiconductor industry.

GF Labs: Our R&D Ecosystem of Partners

Strategic University Partnerships



Government Partnerships



University Partnerships



Consortia / R&D Institutes





Environmental,



Social Governance

GF Commitment to ESG



Environmental

Journey to Zero Carbon: 25% Greenhouse Gas (GHG) emissions reduction by 2030 through.

63K+ annualized metric tons of Carbon equivalent savings achieved in 2019 - 2022

2.2M+ annualized cubic meters water savings achieved in 2019 – 2022

GF named one of "**America's Most Responsible Companies 2023**"

Social

33 total GF Awards in 2020 - 2022 for exceptional performance in CSR and EHS

200 / 200: Perfect scores in 6 of 7 Responsible Business Alliance audits in 2020-2023

World Class: GF TRIR 2020 - 2022 safety rate (≤ 0.14)

GF named one of "**America's Safest Companies**" in 2020*

Governance

Majority independent Board directors

Independent audit, risk, and compliance committee

Experienced global compliance function

Enterprise **risk management framework**

Conflict-free supply chain for 3TG: gold, tantalum, tungsten and tin

GFSHield: a foundation of trust



Beneficial geopolitical landscape

During times of increasing international trade conflicts, GF benefits from the resilience of global scale of operations in stable low-risk geographies (United States, Germany and Singapore)

Pedigree of secure at-scale manufacturing

1. Only pure-play foundry in The United States Department of Defense Trusted Foundry Program
2. ISO 15408 Certification to manufacture Common Criteria Secure Products
3. ISO 27001 Certification for Information Security Management

Intellectual Property (IP) protection

With an industry-leading track record protecting GF IP and customers' IP

**In a world of escalating threats and risks in the technology sector,
our foundation of trust offers a strong competitive edge**

Supply chain responsibility, resiliency and security



Responsible Business Alliance

Advancing Sustainability Globally

100%

of 3TG minerals we use are conflict free

6 of the last 7 RBA validated audit process audits received perfect 200/200 score.



Trusted Supplier to DoD

Critical Supplier - Defense Production Act

Stable and Diverse Geographic Footprint



Our Team



and Culture

Our global team



~13,000
employees

90+
nationalities in
13 countries

415+
new college graduates hired
in 2022

~25%
female workforce

10,500+
employees working in
STEM fields

~82%
employees with university
degrees (PhD, masters,
bachelors)

~81%
engineers, technicians
and operators

GF senior leadership team



Dr. Thomas Caulfield
CEO & President



David Reeder
Chief Financial Officer



Juan Cordovez
Chief Commercial Officer



Mike Hogan
Chief Business Officer



Gregg Bartlett
Chief Technology Officer



KC Ang
Chief Manufacturing Officer



Mike Cadigan
Chief Quality Officer
SVP A&D/Critical Infrastructure



Kevin Soukup
Chief Strategy Officer



Pradheepa Raman
Chief People Officer



Laurie Kelly
Chief Communications Officer



Saam Azar
General Counsel

GF board of directors



Ahmed Yahia
Chairman of the Board



Dr. Thomas Caulfield



Tim Breen



Ahmed Saeed Al Calily



Glenda Dorchak
Independent



Martin L. Edelman



David Kerko
Independent



Jack Lazar
Independent



Elissa Murphy
Independent



Carlos Obeid



Bobby Yerramilli-Rao
Independent



Investing in our team and communities

>12K

hours invested in training our employees in 2022

>4500

GlobalGives employee members

\$1.4M

donated in 2021, includes employee donations with corporate funding

>3600

Employee resource group members worldwide

- ASIA (Asian Society for Inclusion and Awareness)
- BRAG (Black Resource Affinity Group)
- Early Tenure Professionals (ETP)
- GlobalWomen
- GlobalFamilies
- Pride@GF, LGBTQ+ Resource Group
- Remote@GF
- Unidos, Hispanic/Latinx Resource Group
- VRG (Veterans Resource Group)



Our Mission

We innovate and partner with our customers to deliver technology solutions for humanity.

We manufacture semiconductors around the globe.

Our Vision

We are changing the industry that is changing the world.

Our Values



Create

- Innovate beyond what is possible today
- Differentiate our technology to enable customer success
- Have a passion for problem-solving
- Create value for our customers and for our shareholders



Partner

- Collaborate across all borders & boundaries
- Strive for win-win outcomes
- Build trust as the basis of every relationship



Embrace

- Diversity is a competitive advantage
- The best ideas come from being inclusive
- Act with a shared sense of purpose
- Respect everyone



Deliver

- Our customers can count on us to deliver on our commitment
- Work effectively, efficiently and decisively
- Focus on outcomes and are accountable for results
- Celebrate and reward success
- Nothing matters without safety

All with unyielding integrity

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[GF Board of Directors](#)

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GlobalFoundries



GlobalFoundries.Corporate



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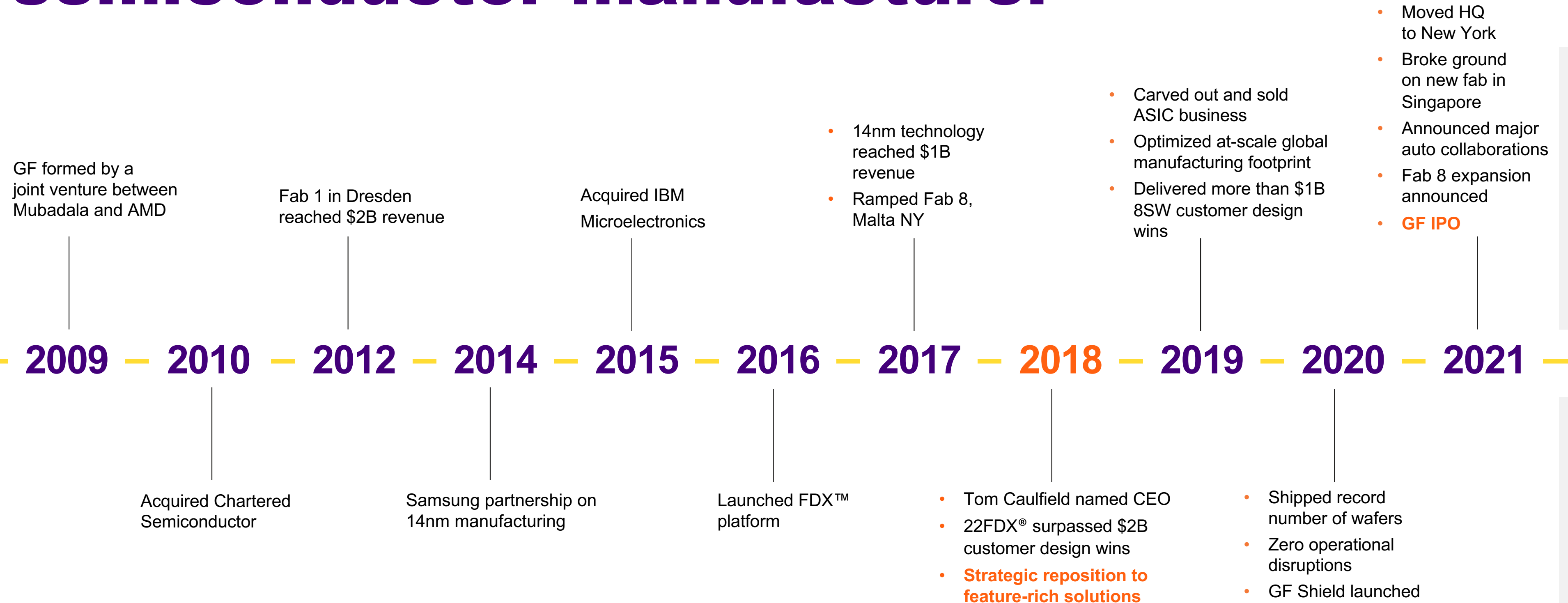
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Appendix

The making of a global semiconductor manufacturer



How we innovate: Industrial & Home IoT

End user applications



Smart home appliances

Smart speaker

Security system

Capabilities required



Intuitive



Pain-free



Efficient



Convenient



Trusted

GF's differentiated performance

FDX[®]

**Feature rich
CMOS**

BCD

NVM

How we innovate: next gen 5G infrastructure

End user applications



Increased range + greater area coverage

Increased data rate + low latency for HD video and AR/VR

Capabilities required



5G sub 8GHz / mmWave



Satellite Communications



Reliability / availability

GF's differentiated performance

SiGe

Feature-rich CMOS

FDX[®]

How we innovate: Smart Mobile Device

End user applications



Hyperconnected human experience bridging physical & digital worlds

Capabilities required



Touch



Hear



See



Trust

GF's differentiated performance

FDX[®]

BCDL[®]

NVM

HV

How we innovate: Industrial & Home IoT

End user applications



Video streaming
Connected camera
Smart home

Capabilities required



Rate



Range



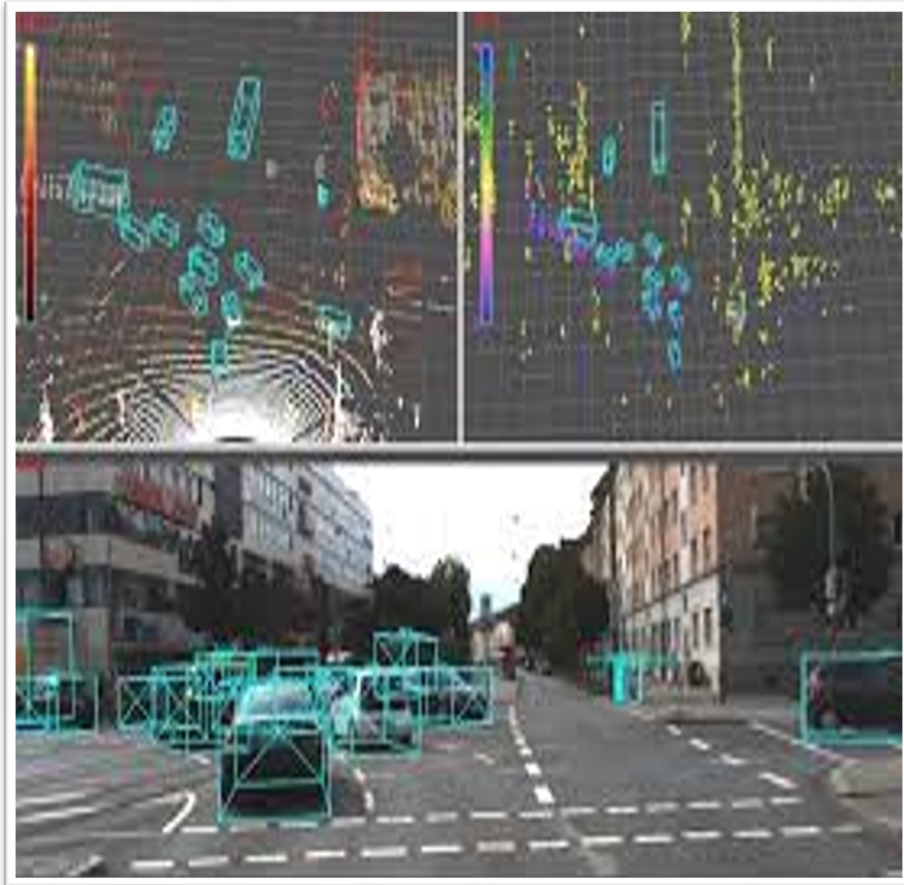
Battery life

GF's differentiated performance

FDX[®]




How we innovate: ADAS

End user applications



Autopilot in highway and urban traffic scenarios

Capabilities required

-  Range
-  Field of view
-  Resolution
-  Robustness
-  Power
-  Intelligence

GF's differentiated performance

FDX[®]
SiGe
Feature-rich CMOS
FinFET

How we innovate: Automotive

End user applications



300+ mile range

Delivering a smartphone like user experience

Time to charge

Capabilities required

Efficient power:



Creation



Conversion



Monitoring

GF's differentiated performance

BCD

**Feature-rich
CMOS**

GaN

Manufacturing operations leadership



KC Ang
Chief Manufacturing Officer



Peter Benyon
SVP and GM Malta, NY Fab



Joseph Chia
VP and GM GIGA+ Singapore Fab



Zhimin Gu
VP, New Singapore Fab
Operations



Manfred Horstmann
SVP and GM European Fabs



Ken McAvey
VP and GM Burlington, VT Fab



Pradip Singh
SVP & GM, Global Manufacturing
Operations Excellence



Yew Kong Tan
SVP and GM Singapore Fabs